



- ★ Super Low Gate Charge
- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

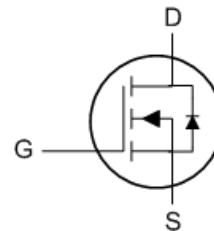
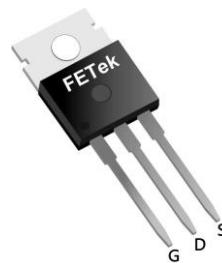
### Product Summary

BVDSS	RDS(ON)	ID
60V	8.5mΩ	75A

### Description

The FKP6032A is the high cell density trenched N-ch MOSFETs, which provide excellent RDS(ON) and gate charge for boost converters and synchronous rectifiers for consumer, industrial power supplies and LED backlighting. The FKP6032A meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

### TO220 Pin Configuration



### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	60	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>c</sub> =25°C	Continuous Drain Current <sup>1,5</sup>	75	A
I <sub>D</sub> @T <sub>c</sub> =100°C	Continuous Drain Current <sup>1,5</sup>	57	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	280	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	80	mJ
I <sub>AS</sub>	Avalanche Current	40	A
P <sub>D</sub> @T <sub>c</sub> =25°C	Total Power Dissipation <sup>4</sup>	89	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-ambient <sup>1</sup>	---	60	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-case <sup>1</sup>	---	1.4	°C/W

Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

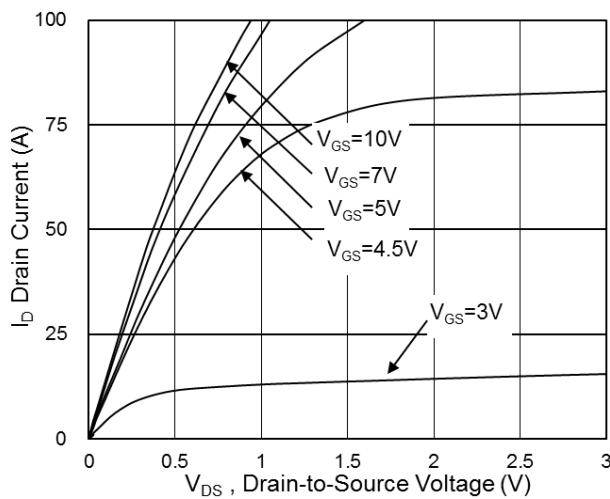
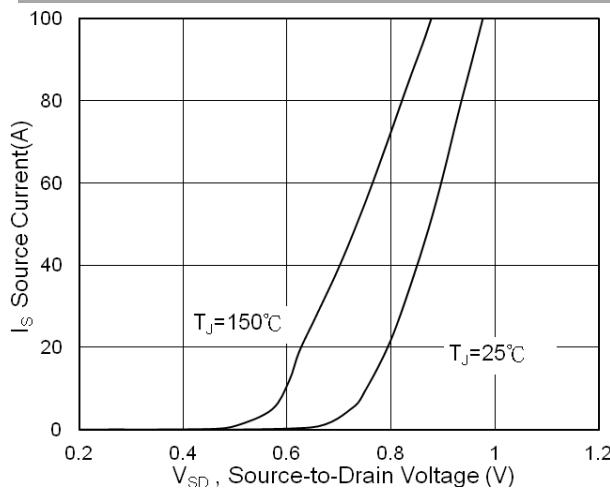
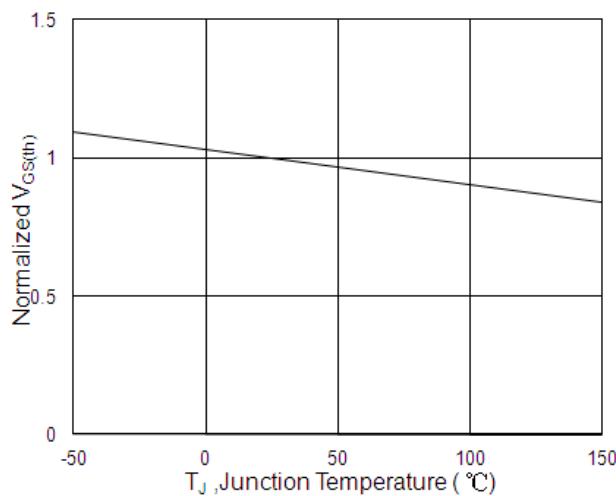
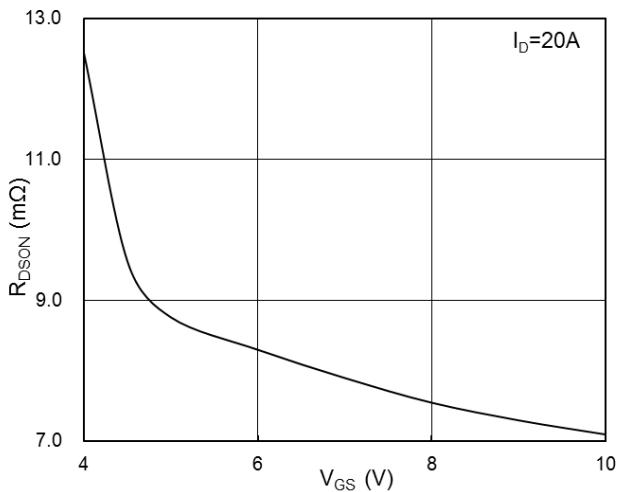
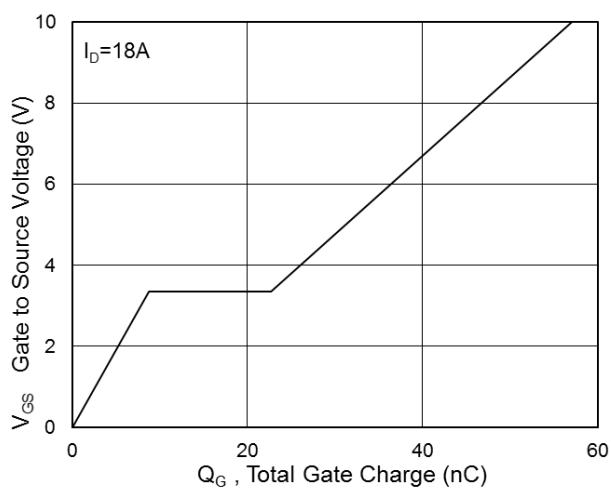
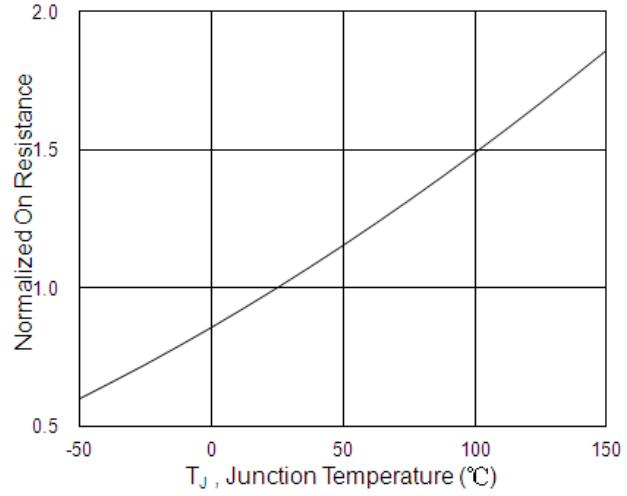
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	60	---	---	V
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=10\text{V}$ , $I_D=20\text{A}$	---	7.1	8.5	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=250\mu\text{A}$	2	---	4.5	V
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=48\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{\text{DS}}=48\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	5	
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$R_g$	Gate Resistance	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	1.2	---	$\Omega$
$Q_g$	Total Gate Charge (10V)	$V_{\text{DS}}=30\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_D=18\text{A}$	---	57	---	nC
$Q_{\text{gs}}$	Gate-Source Charge		---	8.7	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	14	---	
$T_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}}=30\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_G=3.3\Omega$ , $I_D=20\text{A}$	---	16.2	---	ns
$T_r$	Rise Time		---	41.2	---	
$T_{\text{d(off)}}$	Turn-Off Delay Time		---	56.4	---	
$T_f$	Fall Time		---	16.2	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=30\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	3307	---	pF
$C_{\text{oss}}$	Output Capacitance		---	201	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	151	---	

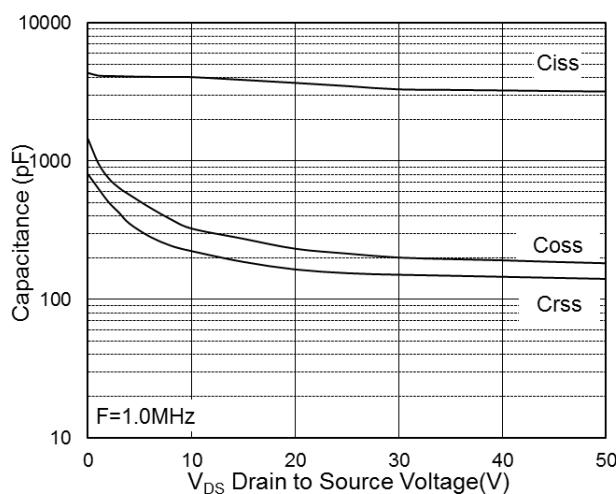
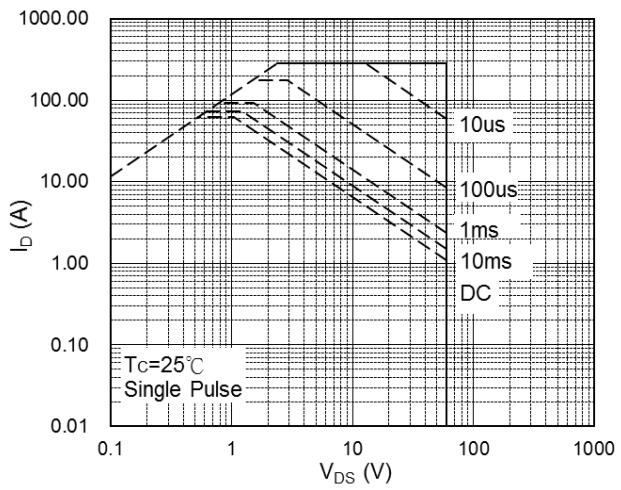
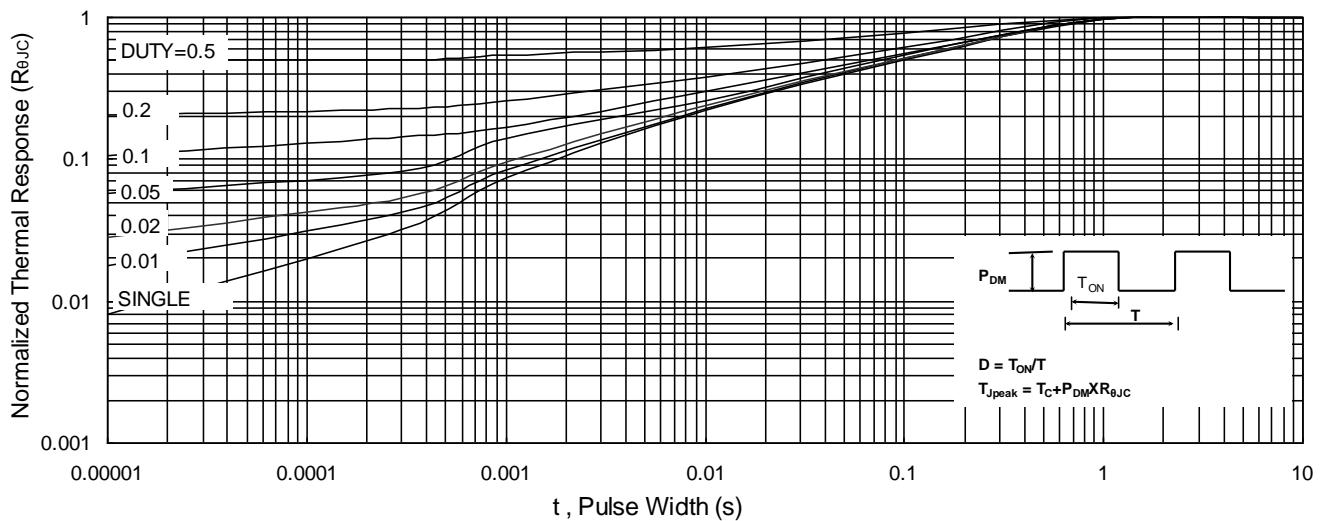
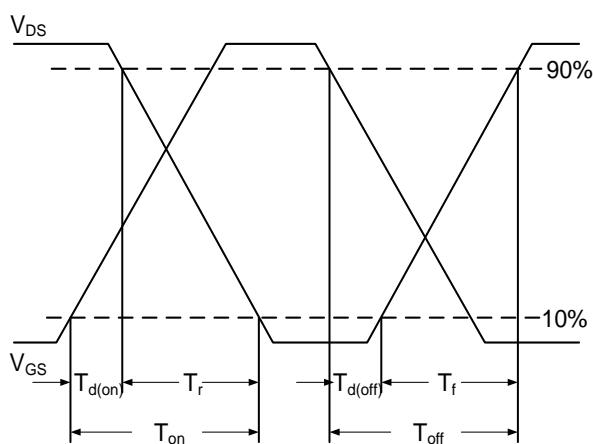
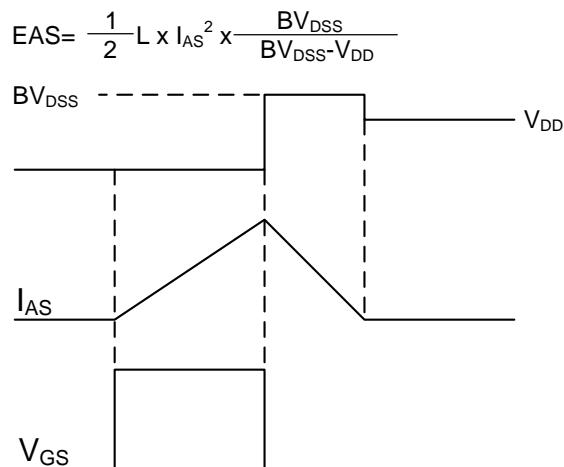
## Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	75	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1.2	V
$t_{\text{rr}}$	Reverse Recovery Time	$I_F=20\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$ , $T_J=25^\circ\text{C}$	---	22	---	nS
$Q_{\text{rr}}$	Reverse Recovery Charge		---	72	---	nC

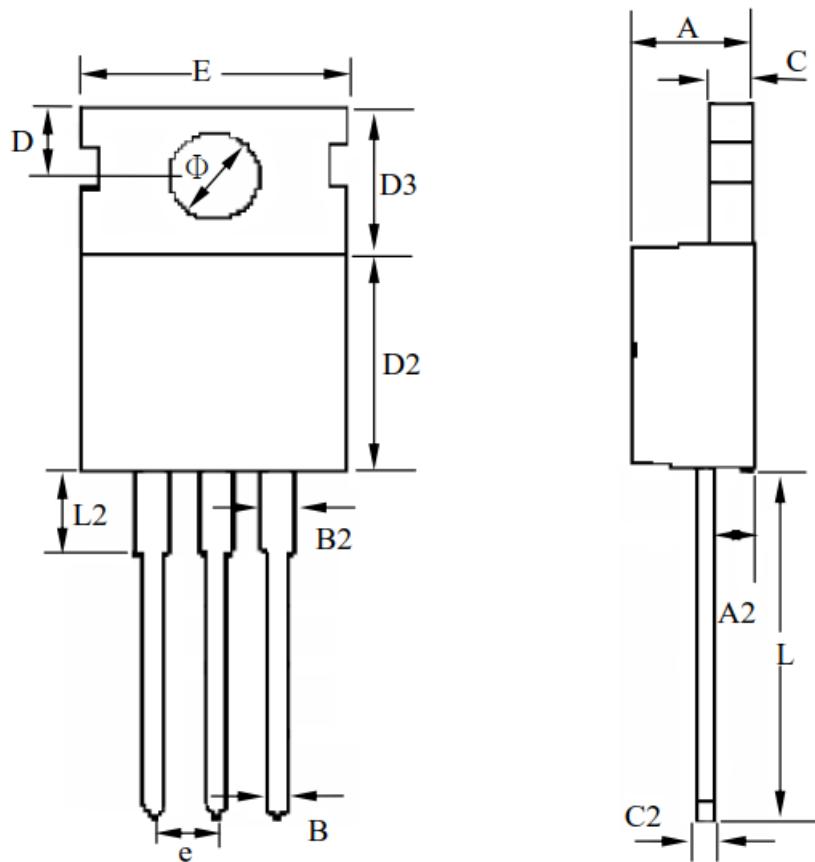
Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=50\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{\text{AS}}=40\text{A}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The maximum current limited by package.

**Typical Characteristics**

**Fig.1 Typical Output Characteristics**

**Fig.3 Source Drain Forward Characteristics**

**Fig.5 Normalized  $V_{GS(th)}$  vs  $T_J$** 

**Fig.2 On-Resistance vs G-S Voltage**

**Fig.4 Gate-Charge Characteristics**

**Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$**


**Fig.7 Capacitance**

**Fig.8 Safe Operating Area**

**Fig.9 Normalized Maximum Transient Thermal Impedance**

**Fig.10 Switching Time Waveform**

**Fig.11 Unclamped Inductive Switching Waveform**

## TO220 Package Outline Dimensions



SYMBOLS	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	4.25	--	4.80	0.167	--	0.189
A2	2.20	--	2.92	0.087	--	0.115
B	0.70	--	0.91	0.028	--	0.036
B2	1.15	--	1.77	0.045	--	0.070
C	1.20	--	1.40	0.047	--	0.055
C2	0.45	--	0.61	0.018	--	0.024
D	2.54	--	3.00	0.100	--	0.118
D2	8.39	--	9.47	0.330	--	0.373
D3	6.30	--	6.70	0.248	--	0.264
E	9.70	--	10.36	0.382	--	0.408
L	12.75	--	14.40	0.502	--	0.567
L2	2.45	--	4.05	0.096	--	0.159
Φ	3.50	--	3.80	0.138	--	0.150
e	--	2.54	--	--	0.100	--